

Technical Data Sheet

YD-3F

CHARACTERISTICS

- Good liquidity, good penetration, Excellent yellowing resistance, good temperature resistance, high bonding strength, low odor and low VOC

FIELDS OF APPLICATION

- Book binding spine glue, suitable for coated paper, Special adhesive for graphic binding. And thickness of book < 10mm.

TECHNICAL DATA

Properties	Specifications	Test Methods
Main ingredients	EVA, Tackifier resins, Wax and Antioxidant	HJ2541-2016
Color	White Translucent	
Form	Flake solid	
Softening point	82 ± 5°C	GB/T15332-1994
Viscosity (180°C)	3100 ± 500 mPa·s	HG/T3660-1999
Open time	< 7s	HG/T3716-2003
Service temperature	155~165°C	

INSTRUCTIONS FOR USE

- The humidity of the workshop should be constant and the relative humidity should be between RH 50% ± 10%
- It is recommended to use the machine with precise temperature control function
- The use temperature should not exceed 180°C for long time as it may reduce the internal performance of the colloid thus affecting the use effect
- It is not recommended to mix with other manufacturers or additive solvent
- In order to avoid the molten glue from contacting the air and carbonization and prevent the contamination of external impurities, the glue tank should be covered tightly at any time
- The storage environment temperature of finished products should be 0~40°C, and should not be placed outside and next to the wall and heat source
- Please contact the supplier immediately if any questions.

SECURITY MATTERS

- It is recommended to operate in a well-ventilated environment

SHELF LIFE AND STORAGE CONDITIONS

- This product shall be stored in a cool and dry place to avoid direct sunlight, the ambient temperature shall be lower than 55°C and away from heat source
- 25kgs/net kraft bag
- Under the above storage conditions, the unopened products shall be stored for 2 years

REMARK

Version number: G03

The corresponding adaptability experiment should be done for the first time use of company's products or process materials to verify whether it is suitable for the proposed process and use.